

### Description

#### Features

- SGT LV MOSFET technology
- Excellent Qg\*Ron product(FOM)
- Extremely low on-resistance(Ron)

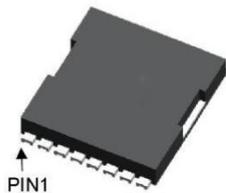
#### Application

- Battery management
- High current switching
- UPS

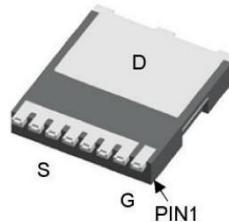
$V_{DS}$	150	V
$R_{ds(on),typ}@V_{gs}=10V$	3.3	m $\Omega$
$I_D$	250	A



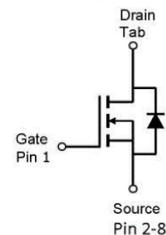
Top View



Bottom View



Pin Configuration



### Package Marking and Ordering Information

Part	Marking	Package	Packing	Reel Size	Tape Width	Qty
HMS250N15LL	HMS250N15LL	Toll-8	Reel	330*28.5mm	24mm	2000pcs

### Key Performance Parameters

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	150	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_c=25^\circ C$	Continuous Drain Current, $V_{GS}=10V$	250	A
$I_D@T_c=100^\circ C$	Continuous Drain Current, $V_{GS}=10V$	175	A
IDM	Pulsed Drain Current	750	A
EAS	Single Pulse Avalanche Energy	1037	mJ
$PD@T_c=25^\circ C$	Total Power Dissipation	416	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_j$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Typ	Max	Units
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient	42	47	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case	0.26	0.3	°C/W

## Electrical Characteristics (T<sub>J</sub>=25 °C, Unless otherwise noted)

Symbol	Parameter	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
BVDSS	Drain-Source Breakdown Voltage	150	--	--	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	--	3.3	4	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =50A
V <sub>GS(th)</sub>	Gate Threshold Voltage	2	3	4	V	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA
IDSS	Drain-Source Leakage Current	--	--	1	uA	V <sub>DS</sub> =150V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C
		--	--	10	uA	V <sub>DS</sub> =120V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C
IGSS	Gate-Source Leakage Current	--	--	±100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
g <sub>fs</sub>	Forward Transconductance	--	96	--	S	V <sub>DS</sub> =10V, I <sub>D</sub> =50A
R <sub>g</sub>	Gate Resistance	--	5	--	Ω	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz
Q <sub>g</sub>	Total Gate Charge	--	115	--	nC	V <sub>DS</sub> =75V, V <sub>GS</sub> =10V, I <sub>D</sub> =50A
Q <sub>gs</sub>	Gate-Source Charge	--	41	--		
Q <sub>gd</sub>	Gate-Drain Charge	--	26	--		
T <sub>d(on)</sub>	Turn-On Delay Time	--	52	--	ns	V <sub>DD</sub> =75V, V <sub>GS</sub> =10V, R <sub>G</sub> =3Ω I <sub>D</sub> =50A
T <sub>r</sub>	Rise Time	--	91	--		
T <sub>d(off)</sub>	Turn-Off Delay Time	--	92	--		
T <sub>f</sub>	Fall Time	--	63	--		
C <sub>iss</sub>	Input Capacitance	--	8090	--	pF	V <sub>DS</sub> =75V, V <sub>GS</sub> =0V, f=1MHz
C <sub>oss</sub>	Output Capacitance	--	806	--		
C <sub>rss</sub>	Reverse Transfer Capacitance	--	29	--		

## Diode Characteristics

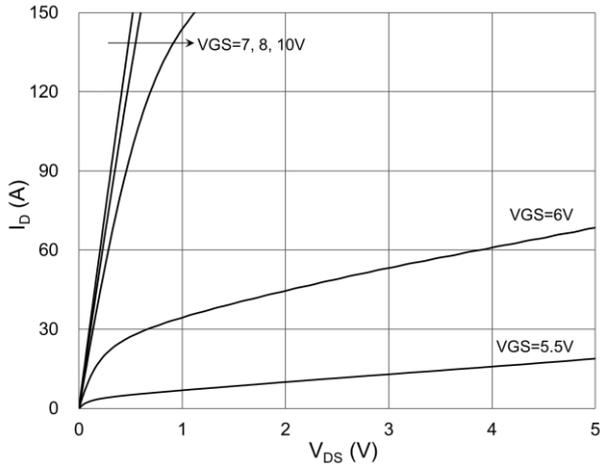
Symbol	Parameter	Conditions	Min	Typ	Max	Units
T <sub>rr</sub>	Body Diode Reverse Recovery Time	I <sub>F</sub> =50A, di/dt=100A/us	--	145	--	ns
Q <sub>rr</sub>	Body Diode Reverse Recovery Charge		--	280	--	nC
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V, I <sub>S</sub> =30A, T <sub>J</sub> =25°C	--	--	1.2	V

Note:

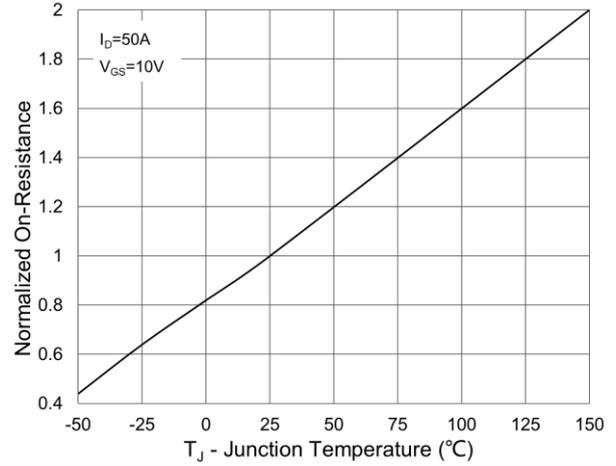
1. Repetitive Rating: Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≅ 300us, duty cycle ≅ 2%.
3. Essentially independent of operating temperature.
4. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=75V, V<sub>GS</sub>=10V, L=0.5mH.

## Typical Performance Characteristics

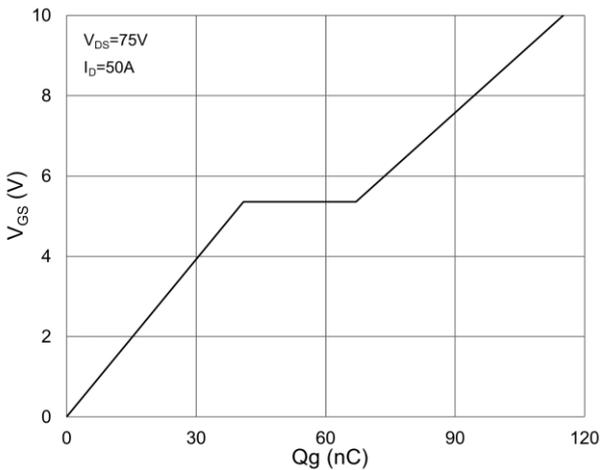
**Fig1 Output Characteristics**



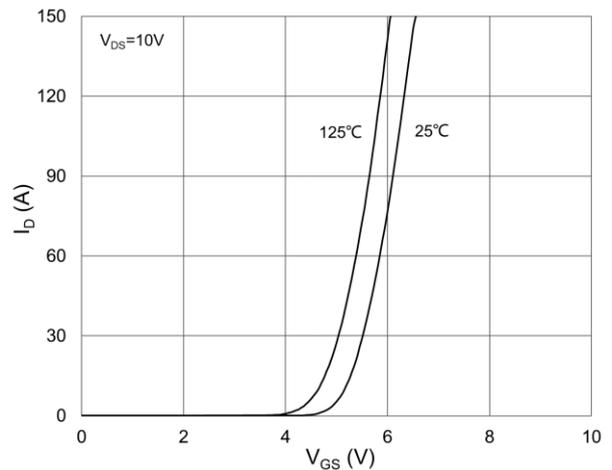
**Fig2 Normalized  $R_{DS(on)}$  vs.  $T_J$**



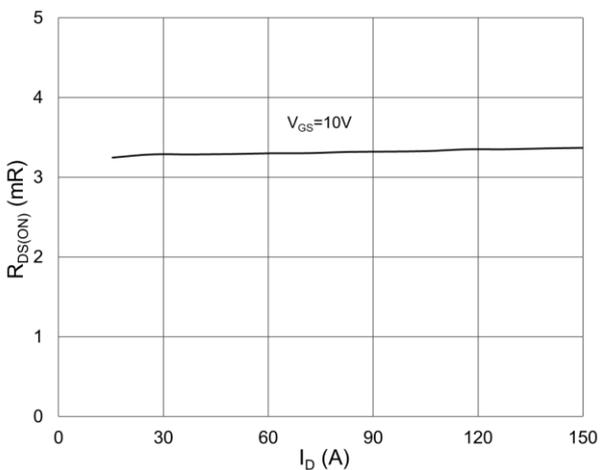
**Fig3 Gate Charge Waveform**



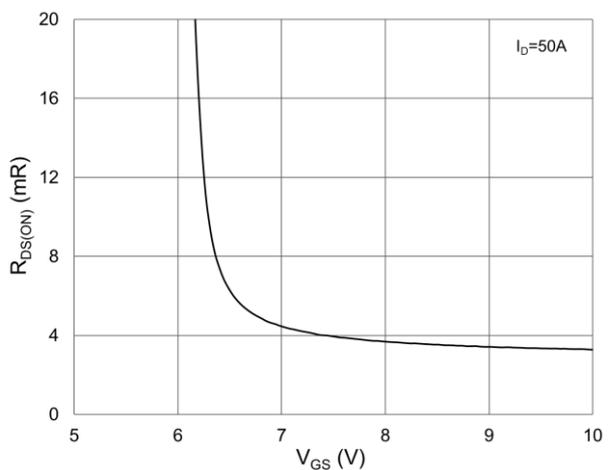
**Fig4 Transfer Characteristics**



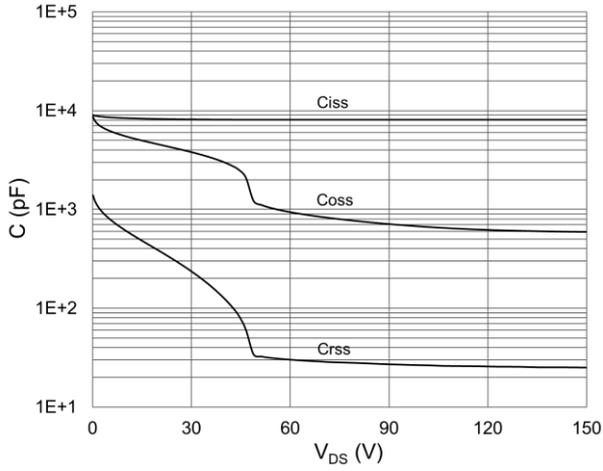
**Fig5  $R_{ds(on)}$  vs. Drain Current and Gate Voltage**



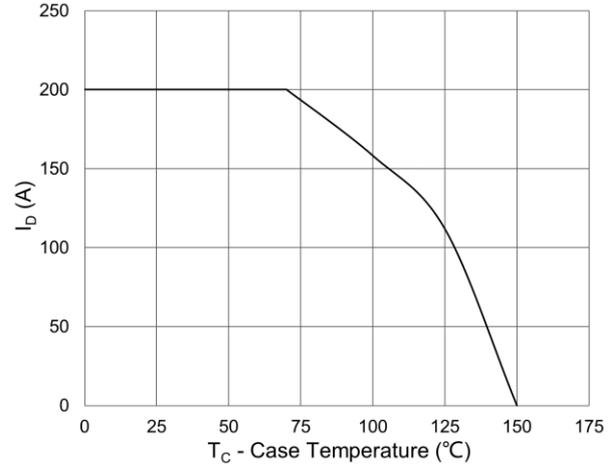
**Fig6  $R_{ds(on)}$  vs. Gate Voltage**



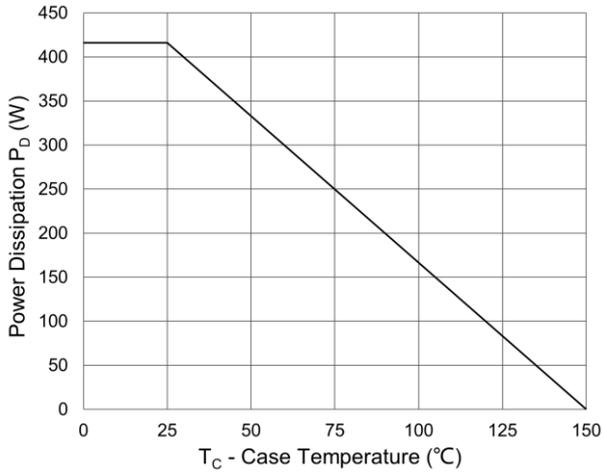
**Fig7 Capacitance Characteristics**



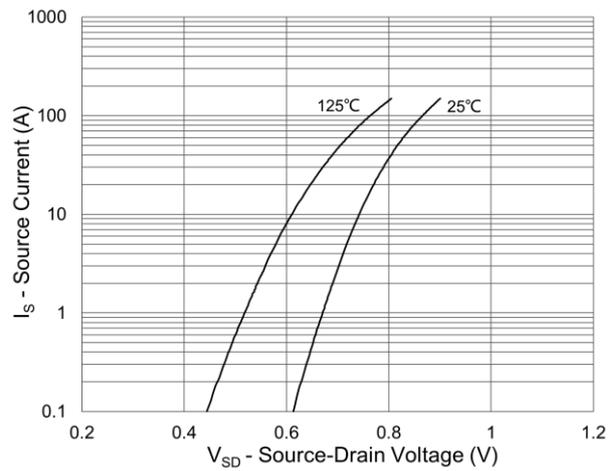
**Fig8 Drain Current Derating**



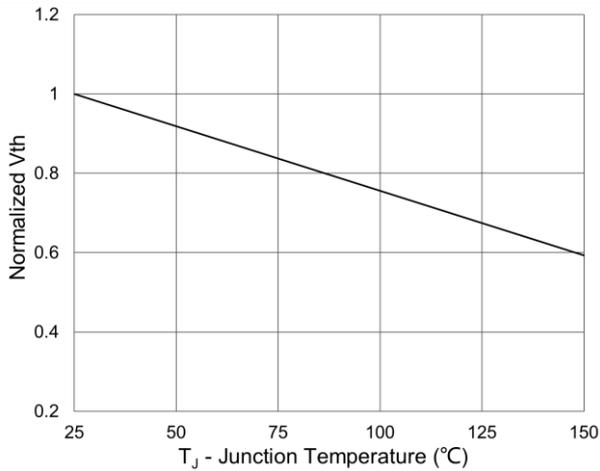
**Fig9 Power Dissipation**



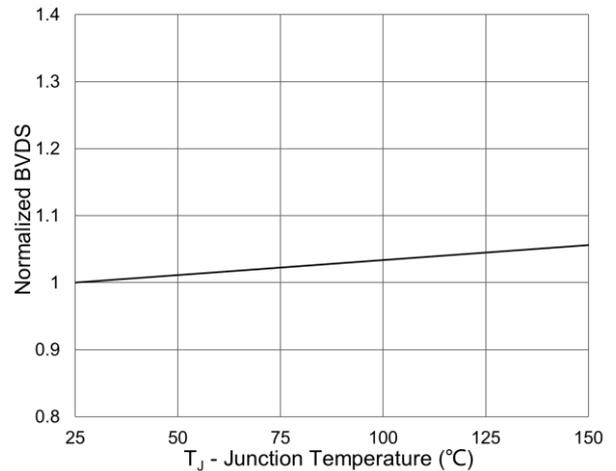
**Fig10 Source-Drain Diode Forward Characteristics**



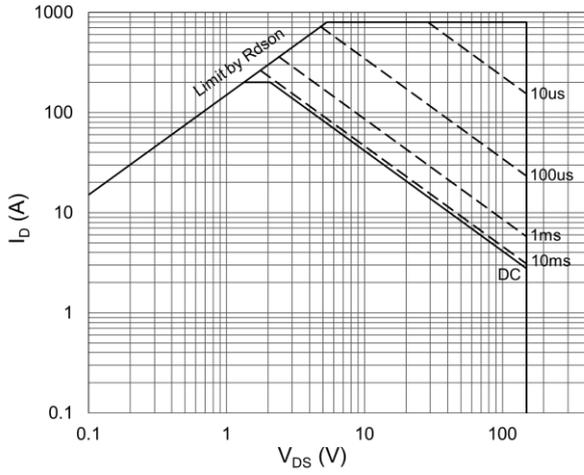
**Fig11 Normalized Threshold Voltage vs. T<sub>J</sub>**



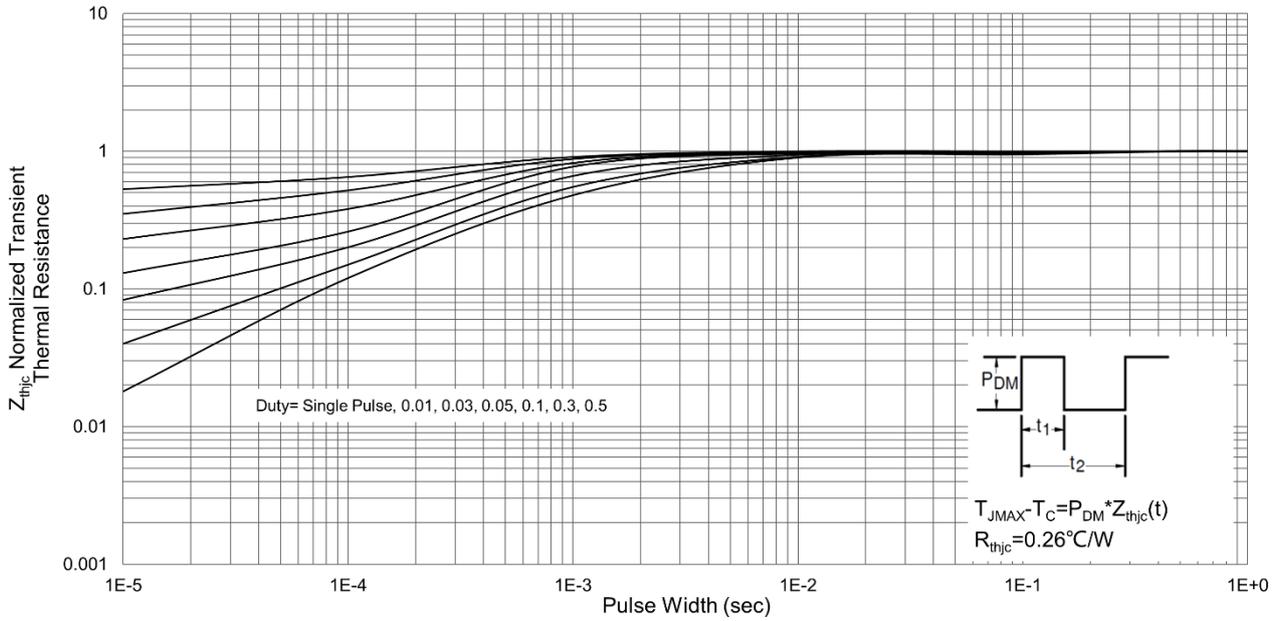
**Fig12 Normalized Breakdown Voltage vs. T<sub>J</sub>**



**Fig13 Maximum Safe Operation Area**

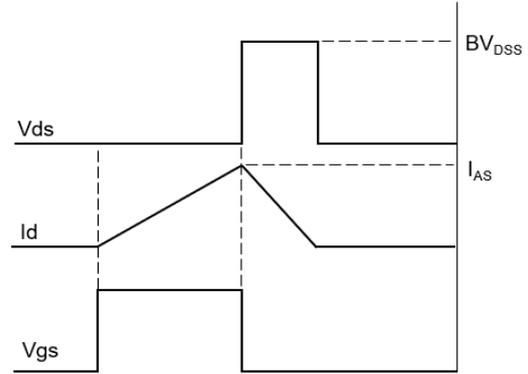
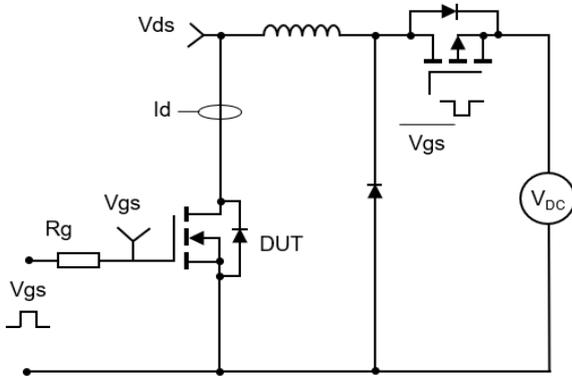


**Fig14 Normalized Transient Impedance**

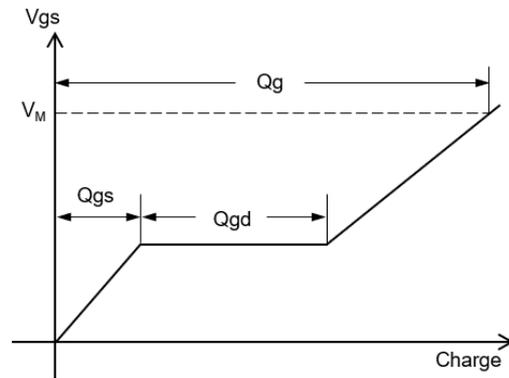
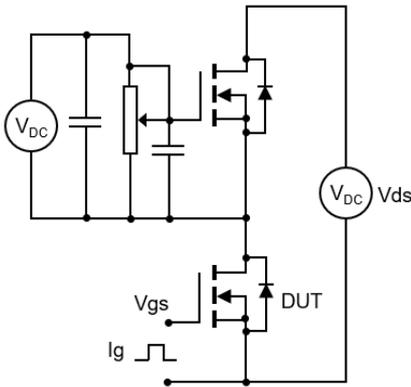


## Test Circuit & Waveform

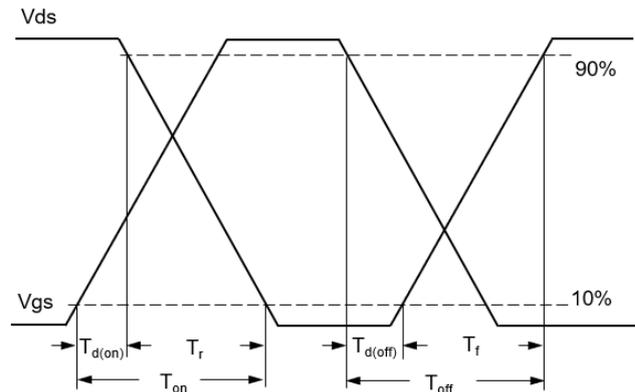
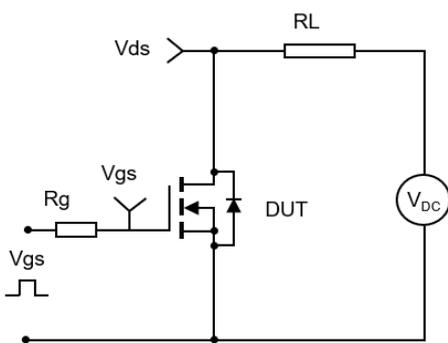
### 1. Unclamped Inductive Switching Test Circuit & Waveform



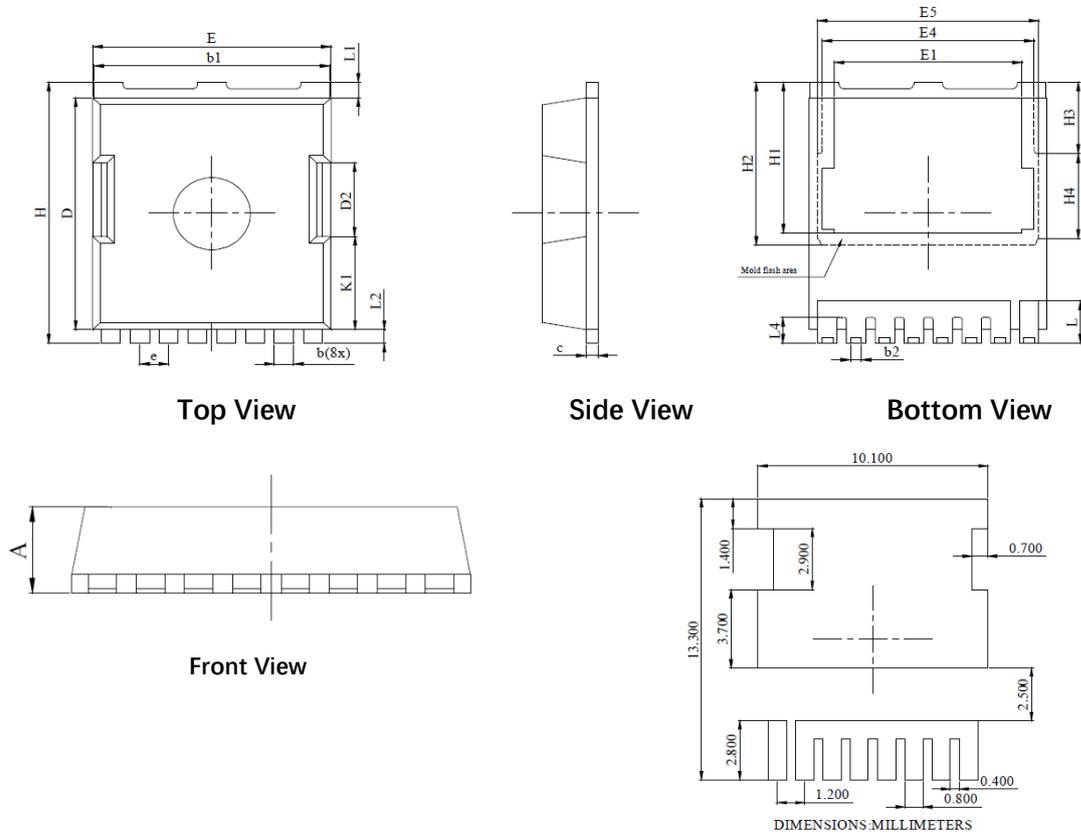
### 2. Gate Charge Test Circuit & Waveform



### 3. Resistive Switching Test Circuit & Waveform



**Toll-8 Package Information**



DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	2.20	2.30	2.40
b	0.70	0.80	0.90
b1	9.70	9.80	9.90
b2	0.42	0.46	0.50
c	0.40	0.50	0.60
D	10.28	10.38	10.58
D2		3.30	
E	9.70	9.90	10.10
E1		7.80	
E4		8.80	
E5		9.20	
e	1.20 (BSC)		
H	11.48	11.68	11.88
H1	6.55	6.75	6.85
H2		7.30	
H3		3.20	
H4		3.80	
K1		4.18	
L	1.70	1.90	2.10
L1		0.70	
L2		0.60	
L4	1.00	1.15	1.30